

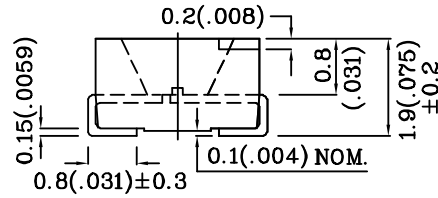
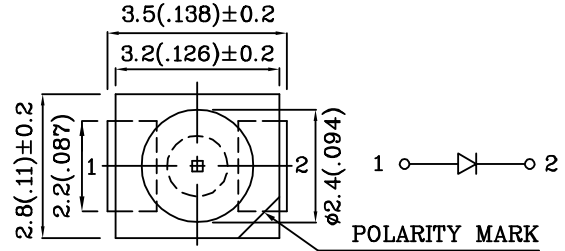
PRELIMINARY SPEC

Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE : 1500PCS / REEL.
- BLACK CASE.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



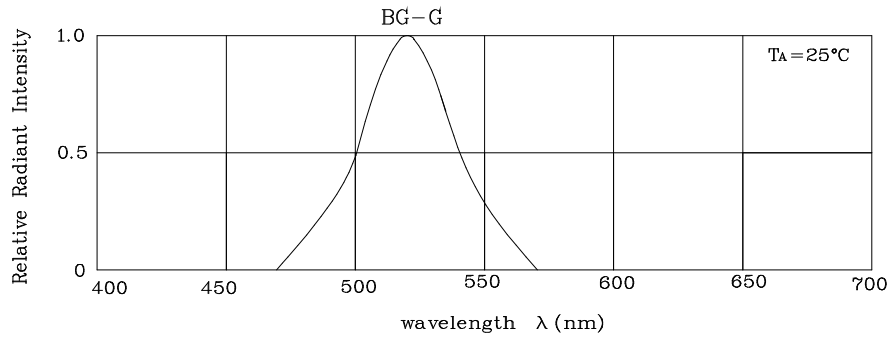
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.

Absolute maximum ratings ($T_A=25^\circ\text{C}$)		BG-G (InGaN)	Unit
Reverse voltage	V_R	5	V
Forward current	I_F	30	mA
Forward current (peak) 1/10Duty cycle 0.1ms pulse width	i_{FS}	150	mA
Power dissipation	P_T	135	mW
Operating temperature	T_A	-40 ~ +85	°C
Storage temperature	T_{stg}	-40 ~ +85	

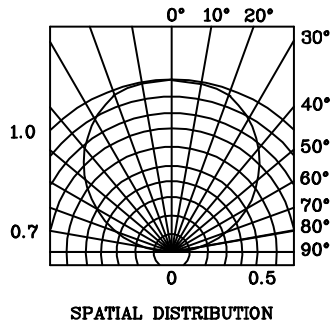
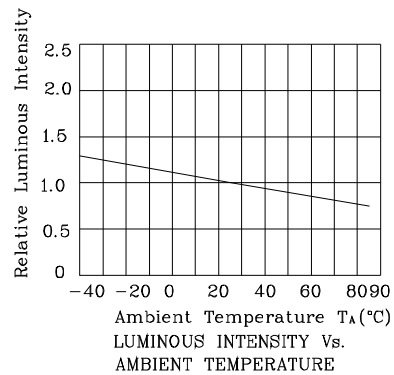
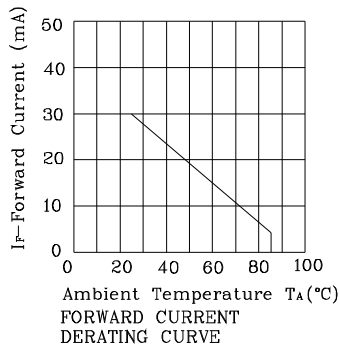
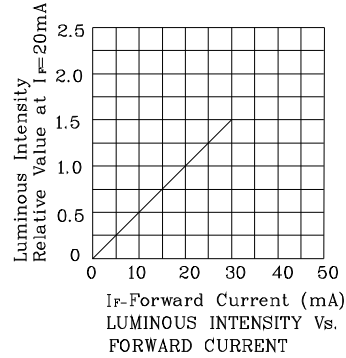
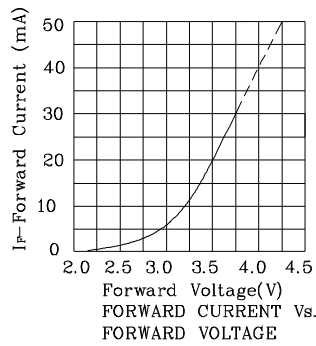
Operating Characteristics ($T_A=25^\circ\text{C}$)		BG-G (InGaN)	Unit
Forward voltage (typ.) ($I_F=20\text{mA}$)	V_F	3.5	V
Forward voltage (max.) ($I_F=20\text{mA}$)	V_F	4.5	V
Reverse current ($V_R=5\text{V}$)	I_R	10	μA
Wavelength at peak emission ($I_F=20\text{mA}$)	λ_{peak}	518	nm
Wavelength at Dominant emission ($I_F=20\text{mA}$)	λ_D	525	nm
Spectral Line half-width ($I_F=20\text{mA}$)	$\Delta\lambda$	36	nm
Capacitance ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	50	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XZBGG45WB	Green	InGaN	Water Clear	110	218	518	120°

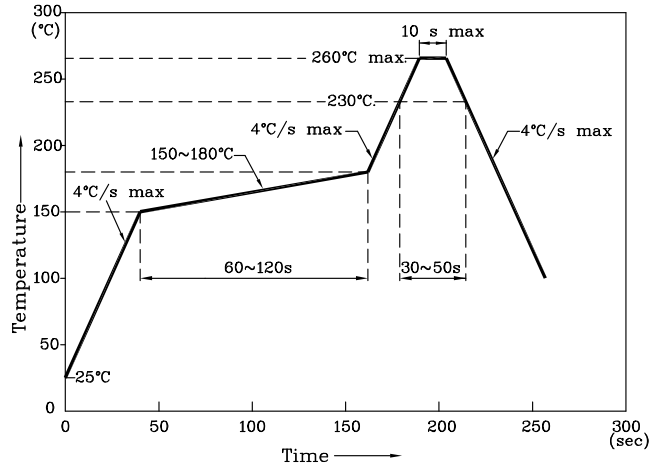


RELATIVE INTENSITY Vs. WAVELENGTH

◆ **BG-G**



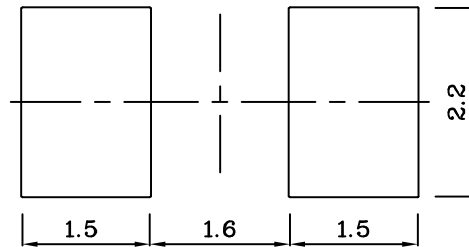
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



❖ Tape Specification (Units : mm)

